



# Product Change Notice

PCN Number: 12-0522-03  
Issue Date: 05-06-2013

Exar Corporation  
[www.exar.com](http://www.exar.com) | Support: [customersupport@exar.com](mailto:customersupport@exar.com)

**PRODUCTS AFFECTED:**

SP510CM-L, SP510EM-L

**CHANGE CATEGORY:**

- |  |   |   |
|--|---|---|
| <input type="checkbox"/> Material        | <input checked="" type="checkbox"/> Process   | <input type="checkbox"/> Package          |
| <input type="checkbox"/> Design          | <input checked="" type="checkbox"/> Datasheet | <input type="checkbox"/> Packing/Shipping |
| <input type="checkbox"/> Other (specify) |   |   |

**DESCRIPTION OF CHANGE:**

Change in wafer fabrication foundry and part numbers.  
Qualification of an alternate qualified wafer foundry, Silan, in addition to the current wafer foundry, Epasil Technologies.

**FROM:**

- Part Numbers:
- SP510CM-L
  - SP510EM-L

**TO:**

- Part Numbers:
- SP510ECF-L
  - SP510EEF-L

Datasheet limits for the following parameters are being changed from:

PARAMETER	OLD SPEC		UNIT
	Low Limit	High Limit	
V.35 Receiver Propagation Delay	NA	30	Ns
Logic Input High	2.0	NA	V

Datasheet limits for the following parameters are being changed to:

PARAMETER	NEW SPEC		UNIT
	Low Limit	High Limit	
V.35 Receiver Propagation Delay	NA	50	Ns
Logic Input High	1.6	NA	V

**IMPACT OF CHANGE:**

None expected for known customer applications.

**TARGET IMPLEMENTATION DATE:** 29-APR-2013

Please contact customer support ([customersupport@exar.com](mailto:customersupport@exar.com)) for sample date availability or qualification data

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